ABSTRACT

The invention relates to a device (1, 1') for treating the surfaces of silicon wafers (2), comprising transport rollers (3) for transporting the silicon wafers (2) on a transport plane (5) which is determined by the transport rollers (3), and at least one conveyor device (3a) which wets the silicon wafer (2) with an aqueous process medium (10). The conveyor device (3a) is arranged in such a manner below the transport plane (5) that it touches the transport plane for wetting the substrate surface, which is oriented in the downward direction, with a process medium (10). Said conveyor device is in direct contact with the substrate surface.